IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	Material Compos © Copyright 2005. IPC international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and M	Ifg Informati	ion		
upplier Info															
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi											2024-05	2024-05-17			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Ste	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*		Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Ste	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number		Mfr Item Number Mfr Item Name				Effective Date	Version	on	Manufacturing Site		Weight*	UOM	Unit Type	
		MT9M114EBLSTCZ- 1 MP 1/6 SOC		1 MP 1/6 SOC CIS	CIS		2024-05-17			CP2		27.085	mg	Each	
Ianufacturin	g Proccess Information	on													
Terminal Plating / Grid Array Material Ter			Perminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature Max Time at Pe		k Tempera	ture Numb	per of Reflow Cyc	eles				
SnAgCu		C	CU Alloy 3				260		C	30	seco	nds 3			
omments															
<b>FTENTION:</b> M	SL 3 Rated item requires	Bake and Dr	ry Pack (after	electrical test)											
or more informa	ation regarding material co	omposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.09	mg		Misc.	proprietary data		0.0155	mg
			Supplier	Silicon (Si)	7440-21-3		4.034	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0405	mg
Die Attach	0.57	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.342	mg
			Supplier	Epoxy resins	129915-35-1		0.114	mg
			Supplier	Acrylic resins	Proprietary Data		0.114	mg
Electrode	0.45	mg	Supplier	Titanium (Ti)	7440-32-6		0.0003	mg
			В	Nickel (Ni)	7440-02-0		0.2679	mg
			Supplier	Gold (Au)	7440-57-5		0.0108	mg
			Supplier	Copper (Cu)	7440-50-8		0.0067	mg
			Supplier	Aluminum (Al)	7429-90-5		0.1643	mg
Glass Lid /Cap	19.46	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.7633	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.73	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		4.6704	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.1406	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.0195	mg
			В	Arsenic Trioxide (As2O3)	1327-53-3		0.1362	mg
Lid Attach	0.005	mg		Photoinitiator	proprietary data		0.0012	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0037	mg
Passivation	0.33	mg	Supplier	Pentaerythritol triacrylate	3524-68-3		0.0495	mg
			Supplier	2-(2-methoxypropoxy)propanol	34590-94-8		0.033	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.033	mg
			Supplier	9-Phenylacridine	602-56-2		0.0165	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.198	mg
Solder Ball	0.42	mg	Supplier	Silver (Ag)	7440-22-4		0.0126	mg
			Supplier	Tin (Sn)	7440-31-5		0.4053	mg
			Supplier	Copper (Cu)	7440-50-8		0.0021	mg
Substrate and Solder Mask	1.76	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.176	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		0.836	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		0.748	mg